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ADV78XX SDRAM memory evaluation

DVP Vid Rx



Memory details- Example

- ◆ **Density – 256 Mbits**
- ◆ **4M x 16Bit x 4Banks(16Mx16)**
- ◆ **Interface- SSTL_2**
- ◆ **Temperature rating 0 -70C**
- ◆ **Package – 66 pin TSOP2**
- ◆ **Lead-Free (RoHS compliant)**

Tests

- ◆ **Memory operation for standard condition:**
 - **3D Comb enabled**
 - **Frame TBC enabled**
- ◆ **Temperature evaluation**
- ◆ **Power supply voltage adjustment**
- ◆ **Continuous Reset**
- ◆ **Timing Parameter adjustment**
- ◆ **Different Board layouts**

Memory operation for standard condition

- ◆ **Memory was initially tested in normal conditions:**
 - **Nominal power supplies**
 - **25 degrees ambient temperature**

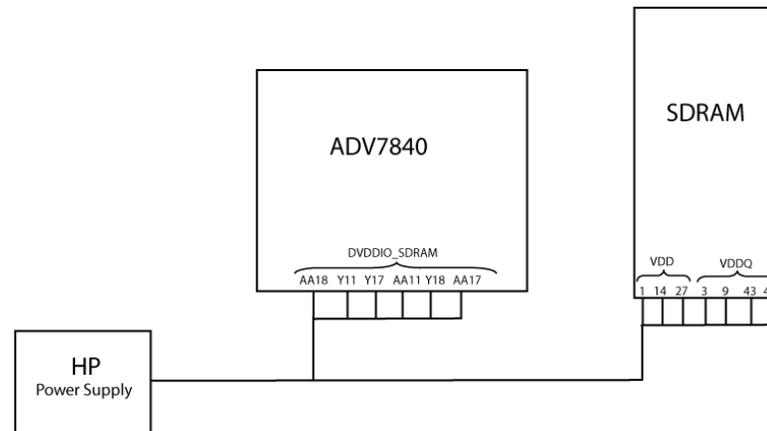
- ◆ **Both FrameTBC and 3D comb were enabled for all the testing**
- ◆ **The tests mainly involve visual inspection for correct operation on screen.**
- ◆ **A BIST test is also used to verify data from the external memory**
 - **BIST – Built in Self test.**
 - **A memory BIST sends data to the memory and checks that it is read back correctly. This fails if any of the data does not match.**

Temperature evaluation

- ◆ **Memory was evaluated for memory range of temperatures: 0 to 70 degrees**
- ◆ **Operation of the memory was observed for full range.**
- ◆ **A BIST test was also used to test for error in the transferred data.**

Power supply voltage adjustment

- ◆ **Memory was evaluated for a range of power supply voltages VDD_3.3V – power supply connected to:**
 - **DVDDIO SDRAM was varied from 2.30V to 2.70V**
 - **VDD supply was also varied from 1.70V to 1.90V**



Continuous Reset

- ◆ **This test is carried out to ensure correct boot up/ reset of the memory controller.**
- ◆ **The ADV78xx issues a reset to the memory controller and the picture is observed. Both Frame TBC and 3D comb are enabled.**
- ◆ **This test is carried out 200+ times**



Timing Parameter adjustment & board layout

- ◆ **To test for any sensitivity of the memory interface to trace lengths etc. Timing adjustments are made to check robustness**
- ◆ **UDQS,LDQS are adjusted relative to data.**
- ◆ **CLK and CLK\ are also adjusted.**

- ◆ **Along with this testing the memory was tested on another generation board. This uses the same memory interface technology, however it is a different board layout.**



Conclusion

- ◆ **Tests completed**
 - **Supply variation- PASS**
 - **Temperature testing -PASS**
 - **Continuously reset -PASS**
 - **Timing parameter adjustment- PASS**
 - **2 difference board layouts - PASS**

- ◆ **No issues were seen in any of the testing.**

- ◆ **For all the testing the memory operated as expected.**